

SCHOTTKY BARRIER RECTIFIER

Absolute Maximum Ratings T_C=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{RRM}	Maximum Repetitive Reverse Voltage	45	V
V _R	Maximum DC Reverse Voltage	45	V
I _{F(AV)}	Average Rectified Forward Current @ T _C = 105°C	20	A
I _{FSM}	Non-repetitive Peak Surge Current (per diode) 60Hz Single Half-Sine Wave	150	A
T _{J.} T _{STG}	Operating Junction and Storage Temperature	-65 to +150	°C

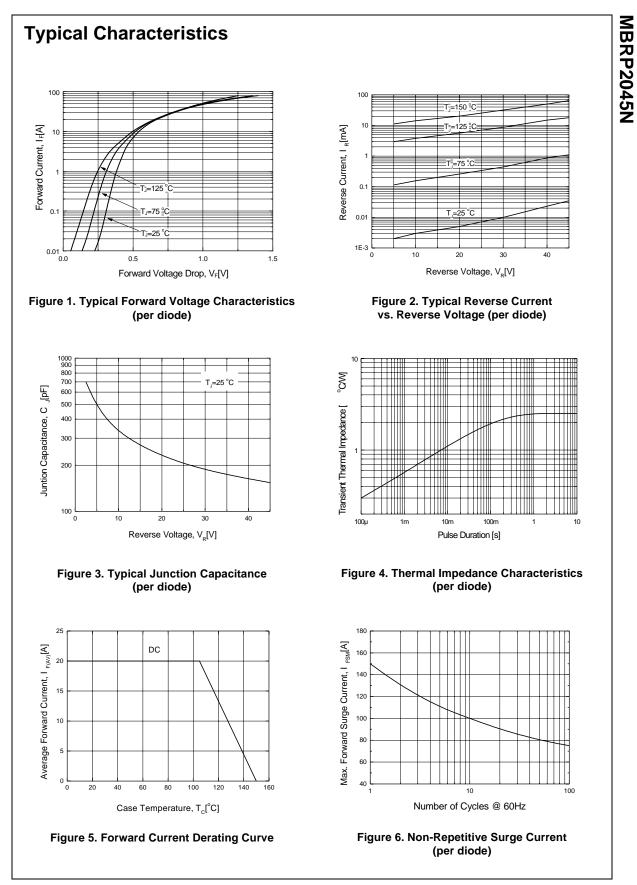
Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{ extsf{ heta}JC}$	Maximum Thermal Resistance, Junction to Case (per diode)	2.5	°C/W

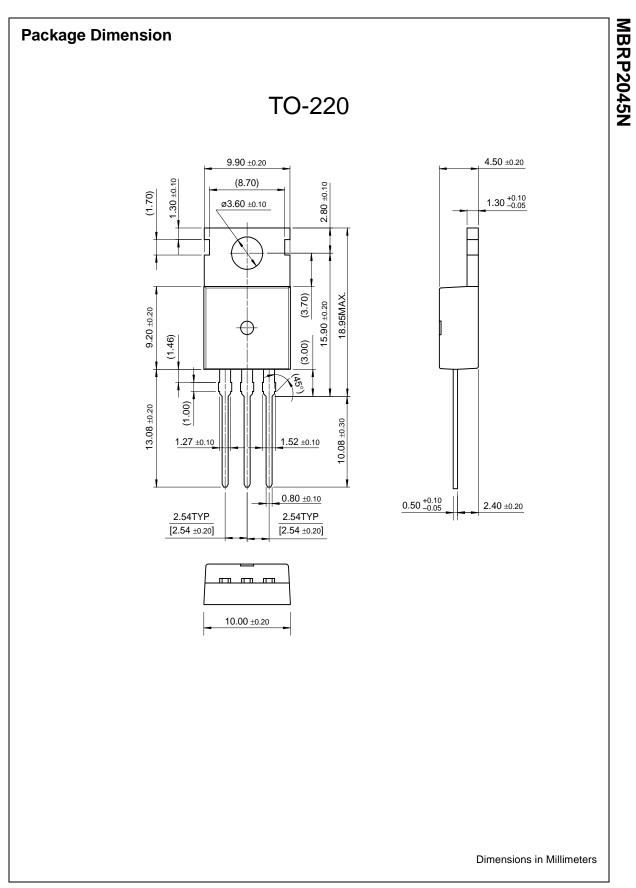
Electrical Characteristics (per diode)

Symbol	Parameter		Value	Units
V _{FM} *	Maximum Instantaneous Forward Voltage			V
	I _F = 10A	T _C = 25 °C	0.65	
	$I_F = 10A$	T _C = 125 °C	0.57	
	$I_F = 20A$	T _C = 25 °C	0.80	
	I _F = 20A	$T_{C} = 25 \text{ °C}$ $T_{C} = 125 \text{ °C}$ $T_{C} = 25 \text{ °C}$ $T_{C} = 125 \text{ °C}$	0.65	
I _{RM} *	Maximum Instantaneous Reverse Current			mA
	@ rated V _R	T _C = 25 °C	1	
		T _C = 25 °C T _C = 125 °C	60	

* Pulse Test: Pulse Width=300µs, Duty Cycle=2%



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CoolFET™	FASTr™	MicroFET™	PowerTrench [®]	SuperSOT™-6
CROSSVOLT™	FRFET™	MicroPak™	QFET [®]	SuperSOT™-8
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EcoSPARK™	GTO™	MSX™	QT Optoelectronics™	TinyLogic®
E ² CMOS [™]	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	l²C™	OCX™	RapidConfigure™	UHC™
Across the board	. Around the world.™	OCXPro™	RapidConnect™	UltraFET®
The Power Franc	hise™	OPTOLOGIC [®]	SILENT SWITCHER [®]	VCX™
Programmable A	ctive Droop™	OPTOPLANAR™	SMART START™	

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